

DATASHEET

3mm Power LED 30-01-B84-YSC-A1T1U1DH-AM

Feature

- RoHS compliant.
- · Piranha package.
- · Colorless clear resin.
- · Low thermal resistance
- Packaged in tubes for automatic insertion equipment.
- Total flux: 7150 to 14250 mlm at 70mA.
- Qualification according to AEC-Q101.
- Compliance with EU REACH.
- Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm).



- · Automotive Lighting
- · Electronic signs and signals
- General lighting application

Device Selection Guide

Chip	Emitted Colon	Desire Colors	
Material	Emitted Color	Resin Color	
AlGaInP	Yellow	Water Clear	





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Product Nomenclature

Prod	uct N	lomei	nclatu	ıre										
30	-	01	-	B8	4	-	YS	С	1.0	A1	T1U1	D	Н	AM
1		2		3	4		5	6		7	8	9	10	11

The product name is designated as below:

1.	Product type
2.	Lead-frame type
3.	Angle
4.	Product pasted without Zener
5.	Chip code
6.	Resin color
7.	Wavelength
8.	Power &Luminous Intensity
9.	Range of Forward Voltage specification
10.	Operation current
11	Application



Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V _R	5	V
Continuous Forward Current	l _F	70	mA
Power Dissipation	P _d	200	mW
Junction Temperature	$T_{\rm j}$	115	${\mathbb C}$
Operating Temperature	Topr	-40 ~ +100	$^{\circ}$ C
Storage Temperature	$T_{ m stg}$	-40 ~ + 100	$^{\circ}$
Thermal Resistance	Rth _{J-A}	150	K/W
ESD	ESD _{HBM}	2000	N/
(Classification acc. AEC Q101)	ESD _{MM}	200	V
Soldering Temperature(T=5 sec)	T _{sol}	Wave Soldering: 26 Hand Soldering: 35	

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Total Flux	Ф۷	7150		14250	Mlm	I _F =70mA
Peak Wavelength	λр		596		nm	I _F =70mA
Dominant Wavelength	λd	587		596	nm	I _F =70mA
Spectrum Radiation Bandwidth	Δλ		15		nm	I _F =70mA
Viewing Angle	2θ _{1/2}		85		deg	I _F =70mA
Forward Voltage	V _F	1.9		2.9	V	I _F =70mA
Reverse Current	I _R			10	μΑ	V _R =10V

Note:

1. Tolerance of Total Flux: ±11%

2. Tolerance of Dominant Wavelength: ±1nm

3. Tolerance of Forward Voltage: ±0.1V

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Bin Range of Dominant Wavelength (Ta=25°C)

Bin	Min.	Max.	Unit	Condition
1	587	590		
2	590	593	nm	I _F =70mA
3	593	596		

Note:

Tolerance of Dominant Wavelength: ±1nm

Bin Range of Forward Voltage (Ta=25°C)

Bin	Min.	Max.	Unit	Condition
2	1.9	2.1		
3	2.1	2.3		
4	2.3	2.5	V	I _F =70mA
5	2.5	2.7		
6	2.7	2.9		

Note:

Tolerance of Forward Voltage: $\pm 0.1V$

Bin Range of Total Flux (Ta=25°C)

Bin	Min.	Max.	Unit	Condition
T1	7150	9000		
T2	9000	11250	Mlm	I _F =70mA
U1	11250	14250		

Note:

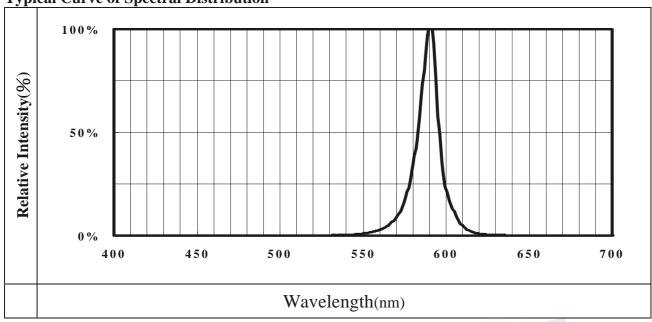
Tolerance of Total Flux: ±11%

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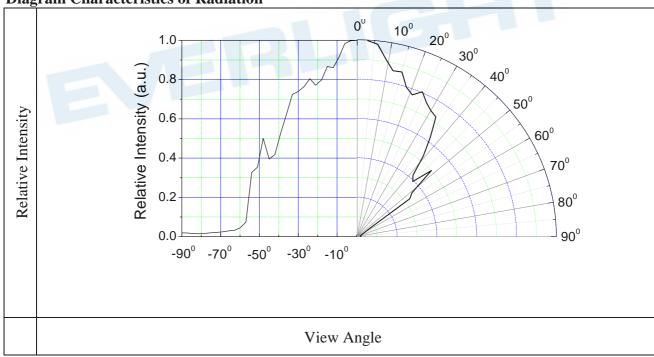


Typical Electro-Optical Characteristics Curves

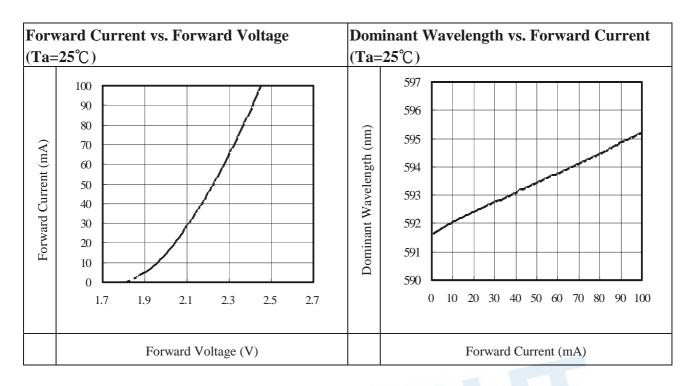
Typical Curve of Spectral Distribution

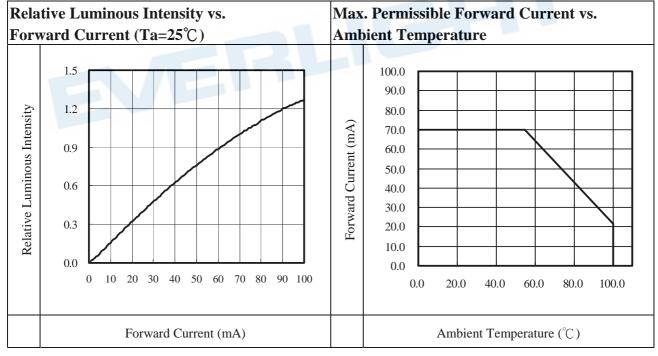






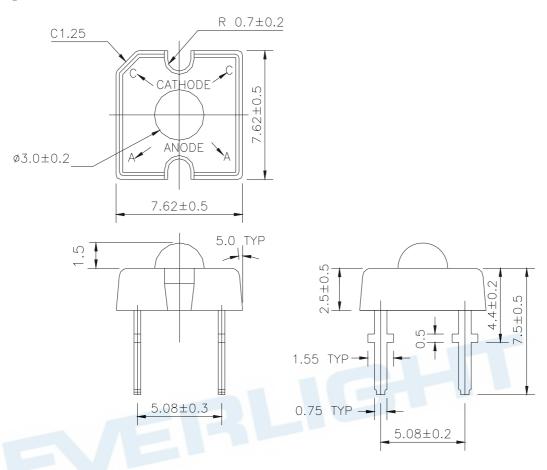








Package Dimension

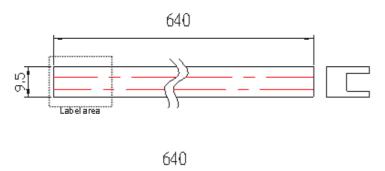


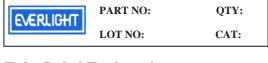
Notes: 1. An epoxy meniscus may extend about 1.5mm(0.059") down the leads

- 2. Tolerances unless dimensions ±0.25mm
- 3. All dimensions are in millimeters



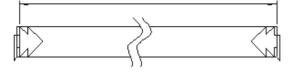
Moisture Resistant Packing Materials Tube





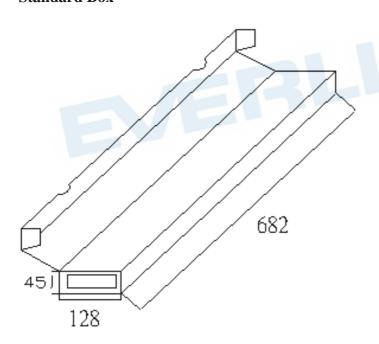
Tube Label Explanation

- PART NO: Product Number
- QTY: Packing Quantity
- LOT No: Lot Number
- CAT: Rank of (VF)(Note*)(Φ V) Note: λ_d /CIE/Color temperature



Note: Tolerances unless mentioned ± 2.0 mm. Unit = mm

Standard Box





Tube Label Explanation

- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Rank of (Note*)

Note: λ_d /CIE/Color temperature

- Luminous Flux(Intensity)
- HUE/REF: Reference
- · LOT No: Lot Number

Note: Tolerances unless mentioned ± 3.0 mm. Unit = mm



Packing Quantity

Packing material	$Length \times Width \times height (mm)$	Tube Quantity (Pcs)	LED Quantity (Pcs)
Tube	640 x 9.5 x12	1	80
Standard box	682 x 128 x 45	36	2880
Large box	702 x 420 x 164	324	25920

Note:

- 1. Normal packing specification is use standard box, unless already defined initially.
- 2. Vacuum packing with anti-static bag after packing in standard box.
- 3. Specifications are subject to change without prior notice.

Notes

1. Lead Forming

- During lead formation, the leads should be bent at a point at least 3mm from the base of the epoxy bulb.
- Lead forming should be done before soldering.
- Avoid stressing the LED package during leads forming. The stress to the base may damage the LED's characteristics or it may break the LEDs.
- Cut the LED leadframes at room temperature. Cutting the leadframes at high temperatures may cause failure of the LEDs.
- When mounting the LEDs onto a PCB, the PCB holes must be aligned exactly with the lead position of the LED. If the LEDs are mounted with stress at the leads, it causes deterioration of the epoxy resin and this will degrade the LEDs.

2. Storage

- The LEDs should be stored at 30°C or less and 60%RH or less after being shipped from Everlight and the storage life limits are 3 months. If the LEDs are stored for 3 months or more, they can be stored for a year in a sealed container with a nitrogen atmosphere and moisture absorbent material.
- Please avoid rapid transitions in ambient temperature, especially, in high humidity environments where condensation can occur.

3. Soldering

■ Careful attention should be paid during soldering. Solder the LED no lower than 1.6mm from the base of stopper is recommended.

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- Avoiding applying any stress to the lead frame while the LEDs are at high temperature particularly when soldering.
- Recommended soldering conditions:

Hand	Soldering	DIP Soldering		
Temp. at tip of iron	300°C Max. (30W Max.)	Preheat temp.	100°C Max. (60 sec Max.)	
Soldering time	3 sec Max.	Bath temp.	260 Max.	
Distance	No lower than 1.6mm from	Bath time.	5 sec Max.	
	the base of stopper			
		Distance	No lower than 1.6mm from	
			the base of stopper	

- Dip and hand soldering should not be done more than one time.
- After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.
- Although the recommended soldering conditions are specified in the above table, dip or handsoldering at the lowest possible temperature is desirable for the LEDs.
- Wave soldering parameter must be set and maintain according to recommended temperature and dwell time in the solder wave.

4. Cleaning

- When necessary, cleaning should occur only with isopropyl alcohol at room temperature for a duration of no more than one minute. Dry at room temperature before use.
- Do not clean the LEDs by the ultrasonic. When it is absolutely necessary, the influence of ultrasonic cleaning on the LEDs depends on factors such as ultrasonic power and the assembled condition. Ultrasonic cleaning shall be pre-qualified to ensure this will not cause damage to the LED

5. Heat Management

- Heat management of LEDs must be taken into consideration during the design stage of LED application. The current should be de-rated appropriately by referring to the de-rating curve found in each product specification.
- The temperature surrounding the LED in the application should be controlled. Please refer to the data sheet de-rating curve.

6. ESD (Electrostatic Discharge)

- Electrostatic discharge (ESD) or surge current (EOS) can damage LEDs.
- An ESD wrist strap, ESD shoe strap or antistatic gloves must be worn whenever handling

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LEDs.

- All devices, equipment and machinery must be properly grounded.
- Use ion blower to neutralize the static charge which might have built up on surface of the LEDs plastic lens as a result of friction between LEDs during storage and handing.

7. Other

- Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
- When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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DISCLAIMER

- 1. EVERLIGHT reserves the right(s) on the adjustment of product material mix for the specification.
- 2. The product meets EVERLIGHT published specification for a period of twelve (12) months from date of shipment.
- 3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
- 4. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from the use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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- This product is not intended to be used for military, aircraft, medical, life sustaining or life saving
 applications or any other application which can result in human injury or death. Please contact
 authorized Everlight sales agent for special application request.

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Revision History

Rev.	Modified date	File modified contents
2	2013/5/8	Change Version format
3	2014/6/30	Change the packing specification
4	2023/9/8	SIX additional statements

